

Finland-Espoo: Miscellaneous general and special-purpose machinery

OJ S 70/2023 07/04/2023

Contract notice

Supplies

Legal Basis:

Directive 2014/24/EU

Section I: Contracting authority

I.1. Name and addresses

Official name: VTT Technical Research Centre of Finland Ltd

National registration number: 2647375-4

Postal address: P.O. Box 1000, VTT

Town: Espoo

NUTS code: FI1 Manner-Suomi

Postal code: 02044

Country: Finland

E-mail: kilpailutus@vtt.fi

Telephone: +358 20722111

Internet address(es):Main address: <https://www.vttresearch.com/en>**I.3. Communication**

The procurement documents are available for unrestricted and full direct access, free of charge, at: <https://tarjouspalvelu.fi/vtt?id=449578&tpk=6ec05378-d4a4-4262-8874-4bb94b7948cf>

Additional information can be obtained from the abovementioned address

Tenders or requests to participate must be submitted electronically via: <https://tarjouspalvelu.fi/vtt?id=449578&tpk=6ec05378-d4a4-4262-8874-4bb94b7948cf>**I.4. Type of the contracting authority**

Body governed by public law

I.5. Main activity

Other activity: Research and development

Section II: Object

II.1. Scope of the procurement**II.1.1. Title**

AUTOMATIC WAFER GRINDER

Reference number: Reg. no 24/206/2023

II.1.2. Main CPV code

42900000 Miscellaneous general and special-purpose machinery

II.1.3. Type of contract

Supplies

II.1.4. Short description

The object of the tender is an Automatic Wafer Grinder, capable of thinning Si and SiC, LiNbO₃ wafers of 100, 150 and 200mm diameter to varying thicknesses with end-point control, cassette-to-cassette processing, TTV profile control and capability to handle thin wafers 100um thick supported by tape and grind away bonded wafer stacks to within 3 um of a typical interface.

The object of the tender process is described in more detail in the invitation to tender documents.

II.1.5. Estimated total value

II.1.6. Information about lots

This contract is divided into lots: no

II.2. Description

II.2.3. Place of performance

NUTS code: FI1 Manner-Suomi

II.2.4. Description of the procurement

The object of the tender is an Automatic Wafer Grinder (later also "Equipment"), capable of thinning Si and SiC, LiNbO₃ wafers of 100, 150 and 200mm diameter to varying thicknesses with end-point control, cassette-to-cassette processing, TTV profile control and capability to handle thin wafers 100um thick supported by tape and grind away bonded wafer stacks to within 3 um of a typical interface.

The technical specification of the equipment to be supplied is discussed in more detail in Annex 1.

The objective is to find one professional supplier that can guarantee a high standard of quality and who is capable of providing the Automatic Wafer Grinder, installation, and user training in its entirety. VTT Technical Research Centre of Finland Ltd will choose one supplier from among the tenderers.

The objective is for the equipment to be supplied by 1st October 2024 at the latest.

II.2.5. Award criteria

Price is not the only award criterion and all criteria are stated only in the procurement documents

II.2.6. Estimated value

II.2.7. Duration of the contract, framework agreement or dynamic purchasing system

Duration in months: 15

This contract is subject to renewal: no

II.2.10. Information about variants

Variants will be accepted: no

II.2.11. Information about options

Options: yes

Description of options:

The options have been described in the invitation to tender documents.

II.2.13. Information about European Union funds

The procurement is related to a project and/or programme financed by European Union funds: no

II.2.14. Additional information

Section III: Legal, economic, financial and technical information

III.1. Conditions for participation

III.1.1. Suitability to pursue the professional activity, including requirements relating to enrolment on professional or trade registers

List and brief description of conditions:

As stated in the invitation to tender documents.

III.1.2. Economic and financial standing

List and brief description of selection criteria:

Selection criteria as stated in the invitation to tender documents

III.1.3. Technical and professional ability

List and brief description of selection criteria:

Selection criteria as stated in the invitation to tender documents

III.2. Conditions related to the contract

III.2.2. Contract performance conditions

As stated in the invitation to tender documents.

Section IV: Procedure

IV.1. Description

IV.1.1. Type of procedure

Open procedure

IV.1.3. Information about a framework agreement or a dynamic purchasing system

IV.1.8. Information about the Government Procurement Agreement (GPA)

The procurement is covered by the Government Procurement Agreement: yes

IV.2. Administrative information

IV.2.2. Time limit for receipt of tenders or requests to participate

Date: 11/05/2023 Local time: 12:00

IV.2.3. Estimated date of dispatch of invitations to tender or to participate to selected candidates

IV.2.4. Languages in which tenders or requests to participate may be submitted

English

IV.2.6. Minimum time frame during which the tenderer must maintain the tender

Tender must be valid until: 30/09/2023

IV.2.7. Conditions for opening of tenders

Date: 11/05/2023 Local time: 12:30

Information about authorised persons and opening procedure: The given date is preliminary. VTT reserves the right to change the scheduled date and time. The opening of tenders shall not be a public event.

Section VI: Complementary information

VI.1. Information about recurrence

This is a recurrent procurement: no

VI.3. Additional information

This notice has links and/or attachments listed in <https://www.hankintailmoitukset.fi/en/public/procurement/85977/notice/125296>

VI.4. Procedures for review

VI.4.1. Review body

Official name: Markkinaoikeus

Postal address: Sörnäistenkatu 1

Town: Helsinki

Postal code: 00580

Country: Finland

E-mail: markkinaoikeus@oikeus.fi

Telephone: +358 295643300

Internet address: <http://www.oikeus.fi/markkinaoikeus>

VI.5. Date of dispatch of this notice

05/04/2023